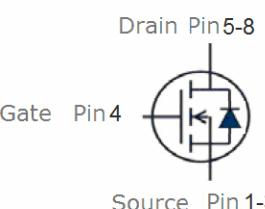


## Features

- N-Channel
- Enhancement mode
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=4.5$  V
- Fast Switching
- 100% Avalanche test
- Pb-free lead plating; RoHS compliant

$V_{DS}$	60	V
$R_{DS(on),TYP}$ @ $V_{GS}=10$ V	6.5	mΩ
$R_{DS(on),TYP}$ @ $V_{GS}=4.5$ V	8.0	mΩ
$I_D$	80	A

PDFN5x6



Part ID	Package Type	Marking	Tape and reel information
VSP009N06MS	PDFN5x6	009N06M	3000pcs/reel

**Maximum ratings**, at  $T_j=25$  °C, unless otherwise specified

Symbol	Parameter	Rating	Unit	
<b>Common Ratings (Tc=25°C Unless Otherwise Noted)</b>				
$V_{GS}$	Gate-Source Voltage	±20	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	60	V	
$T_J$	Maximum Junction Temperature	175	°C	
$T_{STG}$	Storage Temperature Range	-55 to 150	°C	
$I_S$	Diode Continuous Forward Current	$T_c=25$ °C	A	
<b>Mounted on Large Heat Sink</b>				
$I_D$	Continuous Drain current@ $V_{GS}=10$ V	$T_c=25$ °C	80	A
		$T_c=70$ °C	51	A
$I_{DM}$	Pulse Drain Current Tested ①	$T_c=25$ °C	240	A
$P_D$	Maximum Power Dissipation	$T_c=25$ °C	88	W
$R_{JJC}$	Thermal Resistance-Junction to Case		1.7	°C/W
$R_{JJA}$	Thermal Resistance Junction-Ambient		55	°C/W
<b>Drain-Source Avalanche Ratings</b>				
EAS	Avalanche Energy, Single Pulsed ②	196	mJ	

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics @ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	60	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current(T <sub>c</sub> =25°C)	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T <sub>c</sub> =125°C)	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	--	--	100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1	2	3	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	--	6.5	9	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	--	8	12	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, f=1MHz	--	3760	--	pF
C <sub>oss</sub>	Output Capacitance		--	340	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	200	--	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =24V, I <sub>D</sub> =10A, V <sub>GS</sub> =10V	--	82	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	13	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	17	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =30V, I <sub>D</sub> =1A, R <sub>G</sub> =6.8Ω, V <sub>GS</sub> =10V	--	26	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	125	--	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		--	58	--	nS
t <sub>f</sub>	Turn-Off Fall Time		--	112	--	nS
<b>Source- Drain Diode Characteristics@ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
V <sub>SD</sub>	Forward on voltage	I <sub>sd</sub> =30A, V <sub>GS</sub> =0V	--	0.86	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>j</sub> =25°C, I <sub>sd</sub> =10A, V <sub>GS</sub> =0V di/dt=100A/μs	--	38	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge		--	44	--	nC

**NOTE:**

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by T<sub>jmax</sub>, starting T<sub>j</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 28A, V<sub>GS</sub> = 10V. Part not recommended for use above this value
- ③ Pulse width ≤ 300μs; duty cycles≤ 2%.

### Typical Characteristics

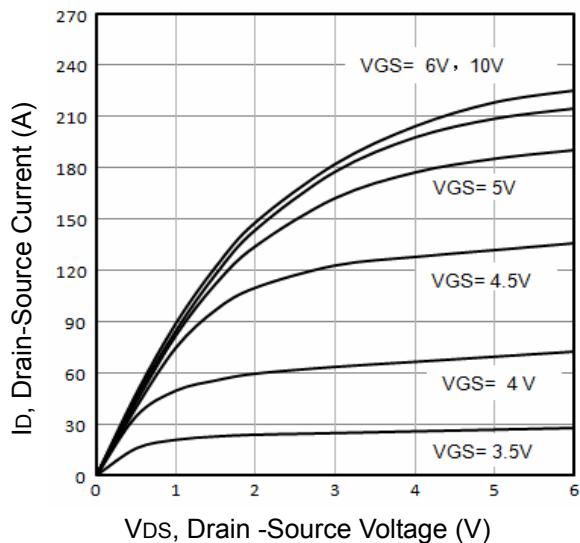


Fig1. Typical Output Characteristics

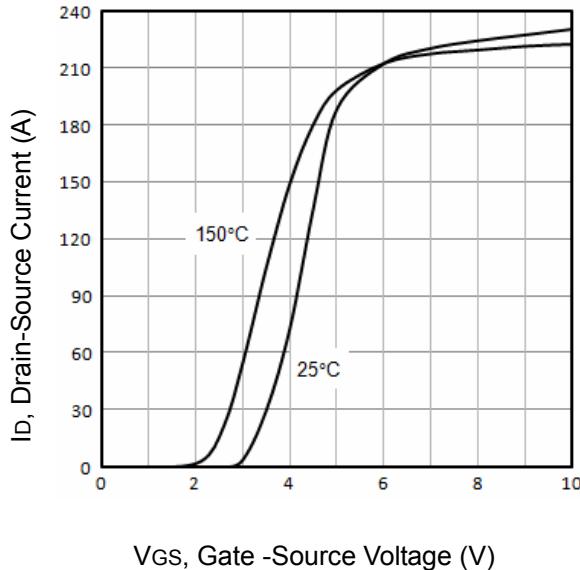


Fig3. Typical Transfer Characteristics

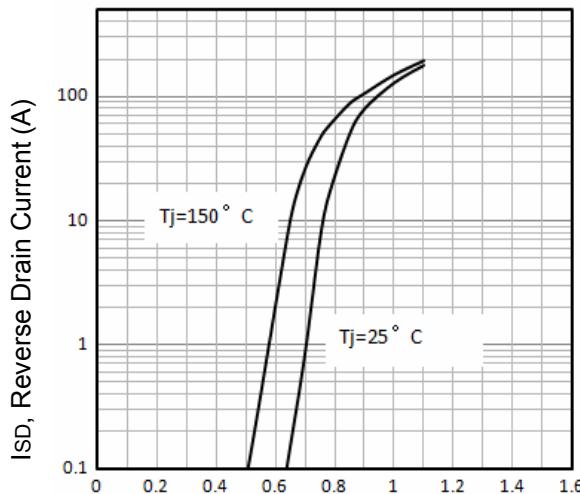


Fig5. Typical Source-Drain Diode Forward Voltage

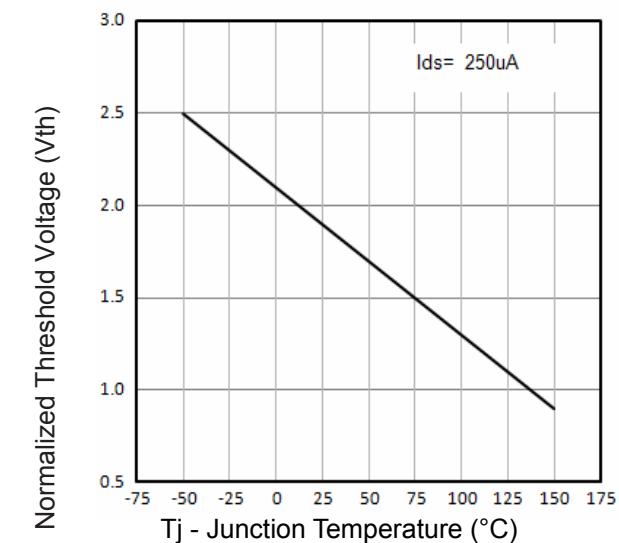


Fig2. Normalized Threshold Voltage Vs.

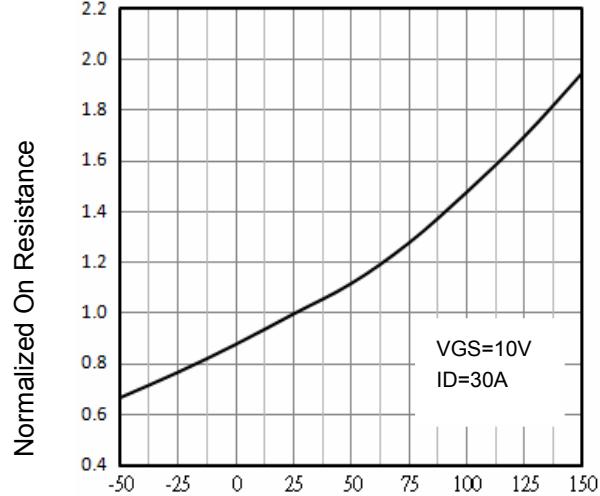


Fig4. Normalized On-Resistance Vs. Temperature

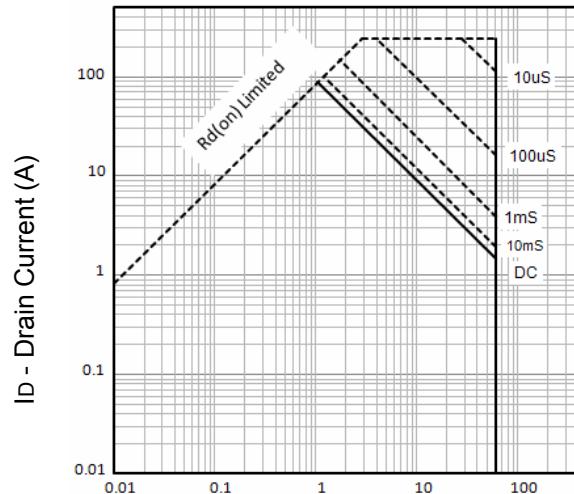


Fig6. Maximum Safe Operating Area

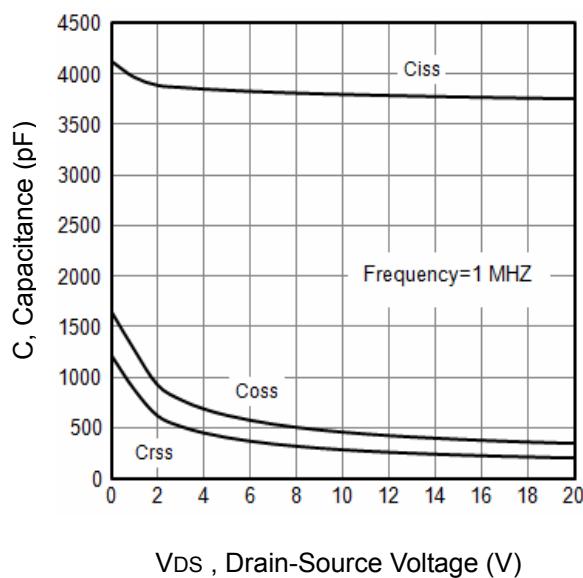


Fig7. Typical Capacitance Vs.Drain-Source Voltage

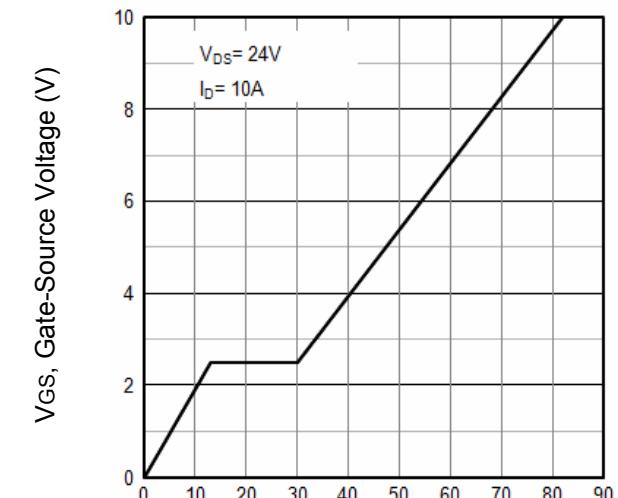


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

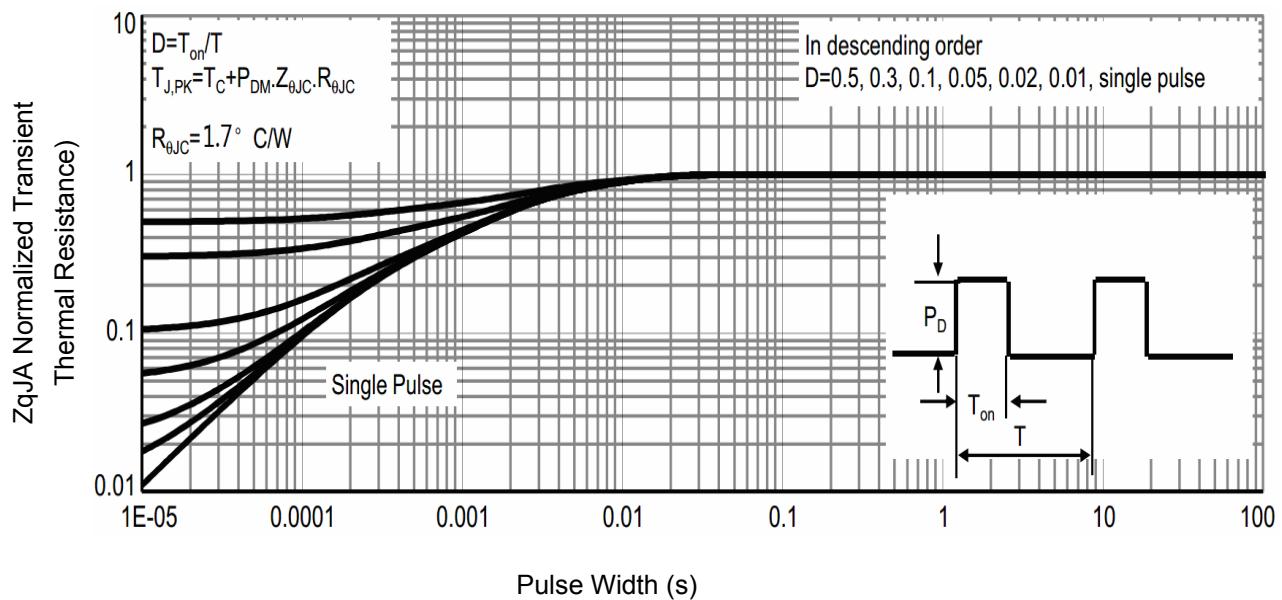


Figure 9: Normalized Maximum Transient Thermal Impedance

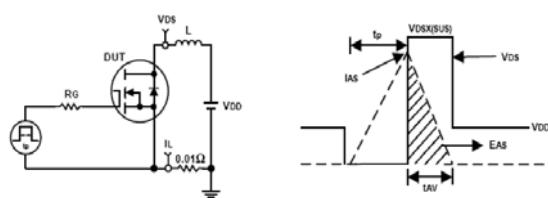


Fig10. Unclamped Inductive Test Circuit and waveforms

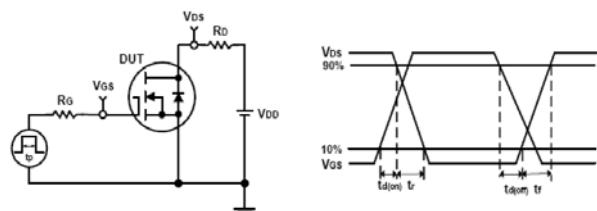
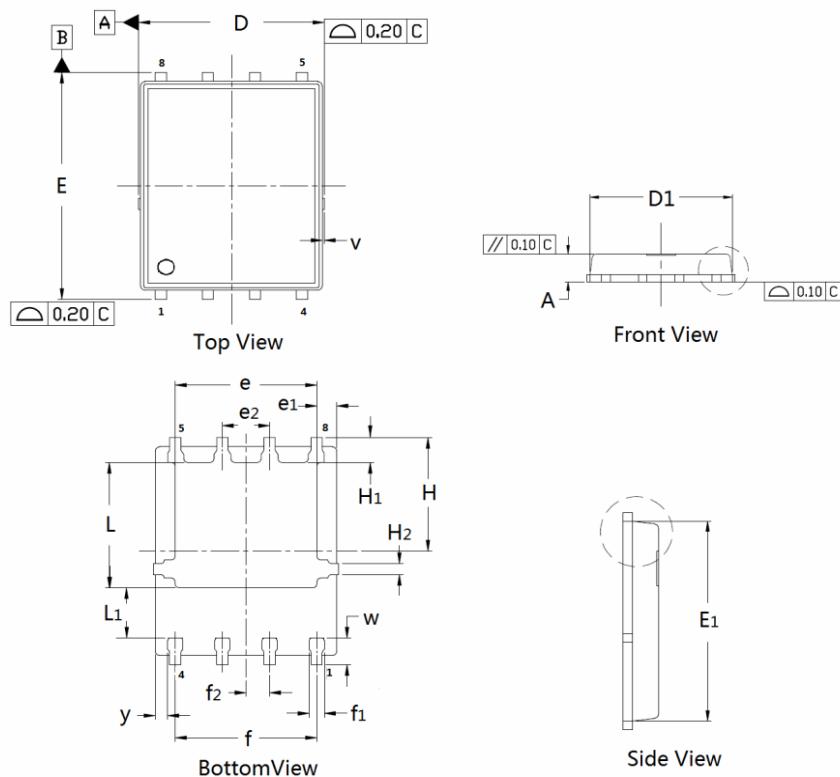


Fig11. Switching Time Test Circuit and waveforms

### PDFN5×6 Package Outline Data



**DIMENSIONS ( unit : mm )**

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.02	1.10	D	4.90	4.98	5.10
D <sub>1</sub>	4.80	4.89	5.00	E	6.00	6.11	6.20
E <sub>1</sub>	5.65	5.74	5.85	e	3.72	3.80	3.92
e <sub>1</sub>	--	0.54	--	e <sub>2</sub>	--	1.27	--
f	--	3.82	--	f <sub>1</sub>	0.31	0.37	0.51
f <sub>2</sub>	--	0.64	--	H	--	3.15	--
H <sub>1</sub>	0.59	0.63	0.79	H <sub>2</sub>	0.26	0.28	0.32
L	3.38	3.45	3.58	L <sub>1</sub>	--	1.39	--
V	--	0.13	--	w	0.64	0.68	0.84
y	--	0.34	--		--	--	--

### Customer Service

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